

Bill of Materials

	SCM	SCC	Remarks
Die Attach	Ablestik 3230	Ablestik 3230	Same BOM
Wire type	Gold MKE UR2	Gold MKE UR2	
Mold Compound	Sumitomo G770	Sumitomo G770	
Lead Finish	Matte Sn	Matte Sn	

Qualification Results Summary for LFCSP Package at STATS ChipPAC China (SCC)

QUALIFICATION RESULT			
Test	Conditions	Sample Size	Result
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 45	PASS
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 45	PASS
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 45	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 45	PASS
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	3/Voltage	PASS ±1250V

*Preconditioned per JEDEC/IPC J-STD-020

Test Correlation Summary

<u>GENERIC NUMBER</u>	<u>FG Part Number</u>	<u>STATUS</u>
AD7173-8	AD7173-8BCPZ	Complete by end of May
AD7173-8	AD7173-8BCPZ-RL	Complete by end of May
AD7175-8	AD70/005Z-0RL	Complete by end of May
AD7175-8	AD7175-8BCPZ	Complete by end of May
AD7175-8	AD7175-8BCPZ-RL	Complete by end of May
ADP5051	ADP5051ACPZ-R7	Pass
ADP5053	ADP5053ACPZ-R7	Pass
ADE7854	ADE7854ACPZ	Pass
ADE7854	ADE7854ACPZ-RL	Pass
ADE7858	ADE7858ACPZ	Pass
ADE7858	ADE7858ACPZ-RL	Pass
ADE7868	ADE7868ACPZ	Pass
ADE7868	ADE7868ACPZ-RL	Pass
ADE7878	ADE7878ACPZ	Pass
ADE7878	ADE7878ACPZ-RL	Pass